VS-42CTQ030SHM3, VS-42CTQ030-1HM3

Vishay Semiconductors

RoHS

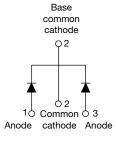
COMPLIANT

HALOGEN

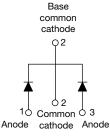
FREE

High Performance Schottky Rectifier, 2 x 20 A









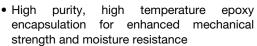
VS-42CTQ030SHM3

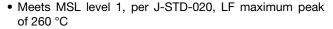
VS-42CTQ030-1HM3

PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 20 A					
V_{R}	30 V					
V _F at I _F	0.38 V					
I _{RM}	183 mA at 125 °C					
T _J max.	150 °C					
E _{AS}	13 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- 150 °C T_J operation
- · Center tap configuration
- Very low forward voltage drop
- High frequency operation
- · Guard ring for enhanced ruggedness and long term reliability





- AEC-Q101 qualified meets JESD 201 class 1A whisker test
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier module has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	CHARACTERISTICS	VALUES	UNITS					
I _{F(AV)}	Rectangular waveform	40	A					
V _{RRM}		30	V					
I _{FSM}	t _p = 5 μs sine	1100	Α					
V _F	20 A _{pk} , T _J = 125 °C (per leg)	0.38	V					
T _J	Range	-55 to 150	°C					

VOLTAGE RATINGS						
PARAMETER SYMBOL VS-42CTQ030SHM3 UNITS						
Maximum DC reverse voltage	V_{R}	30	V			
Maximum working peak reverse voltage	V_{RWM}	30	V			



VS-42CTQ030SHM3, VS-42CTQ030-1HM3

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ABSOLUTE MAXIMUM RATINGS									
PARAMETER		SYMBOL	TEST CONDITIONS		VALUES	UNITS			
Maximum average	per leg								
forward current See fig. 5	per device	I _{F(AV)}	50 % duty cycle at T _C = 121 °0	40	Α				
Maximum peak one cycle n	Maximum peak one cycle non-repetitive 5 μs sine or 3 μs rect. pulse 1		Following any rated load	1100	^				
surge current per leg See fig. 7		I _{FSM}	10 ms sine or 6 ms rect. pulse Condition and with rated V _{RRM} applied		360				
Non-repetitive avalanche energy per leg		E _{AS}	$T_J = 25 ^{\circ}\text{C}$, $I_{AS} = 3 \text{A}$, $L = 2.90 \text{mH}$		13	mJ			
Repetitive avalanche current per leg		I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _R typical		3	Α			

ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CO	VALUES	UNITS			
		20 A	T _{.1} = 25 °C	0.48			
Maximum forward voltage drop per leg	V _{FM} ⁽¹⁾	40 A	11 = 23 0	0.57	V		
See fig. 1	VFM (1)	20 A	T _{.1} = 125 °C	0.38			
		40 A	1J=125 C	0.51			
Maximum reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V Dated V	3	mA		
See fig. 2	IRM \''	T _J = 125 °C	V _R = Rated V _R	183	IIIA		
Threshold Voltage	V _{F(TO)}	T -T movimum		0.22	V		
Forward slope resistance	r _t	T _J =T _J maximum		6.76	mΩ		
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal rang	2840	pF			
Typical series inductance per leg	L _S	Measured lead to lead 5 mi	8.0	nΗ			
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/µs		

Note

 $^{^{(1)}\,}$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHA	THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to 150	°C			
Maximum thermal resistance, junction to case per leg		D	DC operation	2.0				
Maximum thermal resistance, junction to case per package		- R _{thJC}	DC operation	1.0	°C/W			
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.50				
Approximate weight				2	g			
Approximate weight				0.07	oz.			
Maunting targue minimum				6 (5)	kgf · cm			
Mounting torque	maximum			12 (10)	(lbf \cdot in)			
Marking device			Case style D ² PAK (TO-263AB)	42CTQ	030SH			
			Case style TO-262AA	42CTQ	030-1H			



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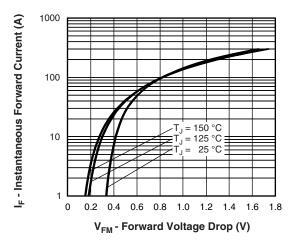


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

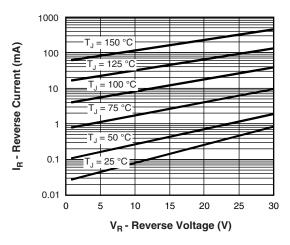


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

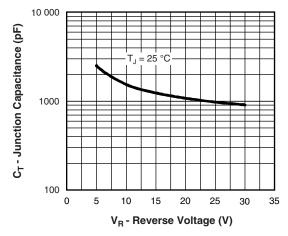


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

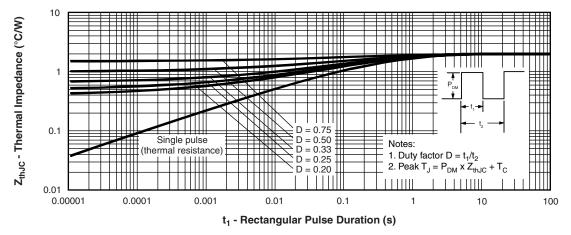


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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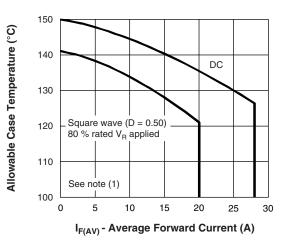


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

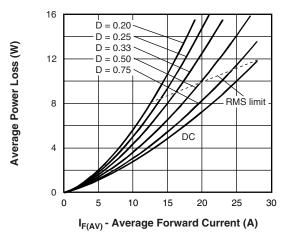


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

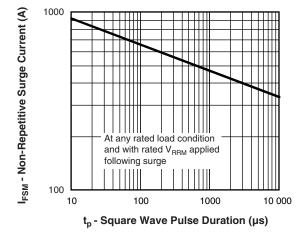


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

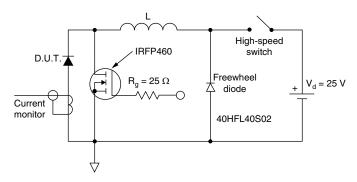


Fig. 8 - Unclamped Inductive Test Circuit

Note

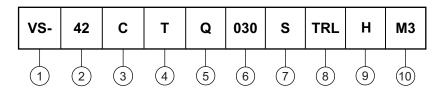
 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = 10 \text{ V} \\ \end{array}$

VS-42CTQ030SHM3, VS-42CTQ030-1HM3

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (40 A)

3 - Circuit configuration: C = Common cathode

4 - T = TO-220

5 - Schottky "Q" series

Voltage rating (030 = 30 V)

7 - • S = D^2PAK (TO-263AB)

• -1 = TO-262AA

8 - • None = Tube

• TRL = Tape and reel (left oriented - for D²PAK only)

• TRR = Tape and reel (right oriented - for D²PAK only)

9 - H = AEC-Q101 qualified

- M3 = Halogen-free, RoHS-compliant and termination lead (Pb)-free

ORDERING INFORMATION								
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-42CTQ030SHM3	50	1000	Antistatic plastic tubes					
VS-42CTQ030STRRHM3	800	800	13" diameter reel					
VS-42CTQ030STRLHM3	800	800	13" diameter reel					
VS-42CTQ030-1HM3	50	1000	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?95046					
Differisions	TO-262AA	www.vishay.com/doc?95419				
Port marking information	TO-263AB (D ² PAK)	www.vishay.com/doc?95444				
Part marking information -	TO-262AA	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?95032				



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	NOTES SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

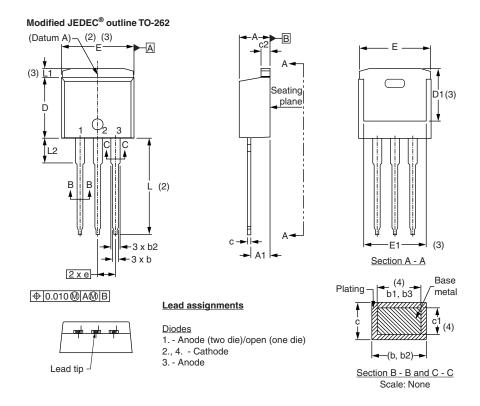
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.10	D BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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Vishay

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